



With heterogeneous integration technology constantly evolving, EVG sheds lights on hybrid bonding and NIL trends – September 11, 2023

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Janet Kang, Taipei; Willis Ke, DIGITIMES Asia Monday 11 September 2023



EV Group's Thomas Uhrmann and Paul Lindner at SEMICON Taiwan 2023. Credit: DIGITIMES

Artificial Intelligence (AI) is driving demand for servers, high-end chips, and advanced packaging, with 3D chips as a potential star in next-generation

advanced packaging technology. In this regard, hybrid bonding technology plays a crucial role in...

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